







Designator	Quantity	Value	Name	Description	Footprint	Model:Footprint	LibRef
C1, C3	2	2 1uF	Сар	Capacitor	CAPC_0603_1608X 08L	Chip Capacitor 0603	Сар
C2, C33	2	2 100nF	Сар	Capacitor	CAPC_0603_1608X 08L	Clip Capacitor 0003	Сар
C37, C38, C40, C41	4	1 22uF	Сар	Capacitor	CAPC_1206_3216X 16L	Clip Capacitor 1200	Сар
C42		1 100pF	Сар	Capacitor	CAPC_0603_1608X 08L	Chip Capacitor 0603	Сар
D1	•	1	Schottky 40V 3A	Schottky Diode	SOD123	SOD123	D Schottky
D2		1	TVS	Schottky Diode	SODFL350X120-2L	SODFL, 2-Leads, Body 1.60x3.50mm, IPC High Density	D Zener
ESP1		1	ESP8266 ESP-12-E	ESP8266 ESP-12-E	ESP8266 ESP-12-E	ESP8266 ESP-12-E	ESP8266 ESP-12-E
12		1 15uH	Inductor	Inductor	INDP4949X30N	Precision Wire Wound Inductor, 2-Leads, Body 4.90x4.90mm, IPCMedium Density	Inductor
LED1		1	RGB LED Common anode	Dot is _not_anode!	PLCC-4	LED .	RGB_LED
Q1, Q2, Q3	;	3	MOSFET-P		DPAK229P994X24 1-3L	D-PAK, 3-Pads, Body 6.21x6.73mm (max), IPCHigh Density	
Q4		1	MOSFET-N		SOT23	SOT23, 3-Leads, Body 2.90x2.45mm, Pitch 0.95mm, IPC High Density	MOSFET-N
R1, R2, R3, R4, R5, R14	(5 10K	Res2	Resistor	RESC_0603_1608X 08L	Chip Resistor, 2-Leads, Body 1.60x0.80mm, IPCHigh Density	Res2
R6, R7, R8, R9, R13		5 1K	Res2	Resistor	RESC_0603_1608X 08L	Chip Resistor, 2-Leads, Body 1.60x0.80mm, IPCHigh Density	Res2
R11		1 220K	Res2	Resistor	RESC_0603_1608X 08L	Chip Resistor, 2-Leads, Body 1.60x0.80mm, IPCHigh Density	Res2
R12		1 100K	Res2	Resistor	RESC_0603_1608X 08L	Chip Resistor, 2-Leads, Body 1.60x0.80mm, IPCHigh Density	Res2
R29	,	1 2.4K	Res2	Resistor	RESC_0603_1608X 08L	Chip Resistor, 2-Leads, Body 1.60x0.80mm, IPCHigh Density	Res2
R30		1 680R	Res2	Resistor	RESC_0603_1608X 08L	Chip Resistor, 2-Leads, Body 1.60x0.80mm, IPCHigh Density	Res2
S_FUN1	,	1	4-1437565-1	Tactile switch	EVQP7001P	Sde actuated tactile switch	4-1437565-1
U1		1	M74VHC1GT125	Level shifter non inverting	SOT95P285X130- 5N	SOT23, 5-Leads, Body 3.00x2.85mm, Pitch 0.95mm, IPC Medium Density	M74VHC1GT125
U2		1	AP7383-50W5		SOT95P285X130- 5N	SOT23, 5-Leads, Body 3.00x2.85mm, Pitch 0.95mm, IPC Medium Density	AP7383-50W5
U3		1	BD9G101G-LB		TSOP95P280X125- 6L	TSOP, 6-Leads, Body 2.90x1.65mm, Pitch 0.95mm, IPCHigh Density	BD9G102G-LB

Design Rules Verification Reporl Filename : E:\dev\wifi-christmas-tree-lights\pcbs\controller_8266\controller_8266.PcbDoc

Warnings 4 Rule Violations 0

Warnings	
Unplated multi-layer pad(s) detected	4
Total	4

Rule Violations	
Clearance Constraint (Gap=0.127mm) (All),(IsKeepOut)	0
Clearance Constraint (Gap=0.127mm) (All),(All)	0
Clearance Constraint (Gap=-0.1mm) (InPadClass('AGND_TIE')), (InNet('GND') And OnBottomLayer	0
Short-Circuit Constraint (Allowed=No) (All),(All)	0
Short-Circuit Constraint (Allowed=Yes) (InPadClass('AGND_TIE')),(InNet('GND')	0
Un-Routed Net Constraint ((All))	0
Modified Polygon (Allow modified: No), (Allow shelved: No)	0
Width Constraint (Min=0.127mm) (Max=1.27mm) (Preferred=0.127mm) (All	0
Routing Via (Templates Used To Check Via: gnd_stitch, power_via, signal_routing) (All	0
Power Plane Connect Rule(Relief Connect)(Expansion=0.508mm) (Conductor Width=0.127mm) (Air Gap=0.127mm	0
Minimum Annular Ring (Minimum=0.13mm) (IsPad;	0
Minimum Annular Ring (Minimum=0.13mm) (IsVia)	0
Acute Angle Constraint [Tracks Only] (Minimum=45.000) (All	0
Hole Size Constraint (Min=0.3mm) (Max=6.3mm) (All)	0
Hole To Hole Clearance (Gap=0.2mm) (All),(All)	0
Minimum Solder Mask Sliver (Gap=0.2mm) (All),(All)	0
Net Antennae (Tolerance=0mm) (All)	0
Board Clearance Constraint (Gap=0mm) (InLayerClass('Electrical Layers')	0
Component Clearance Constraint (Horizontal Gap = 0mm, Vertical Gap = Infinite) (All),(All)	0
Component Clearance Constraint (Horizontal Gap = 0mm, Vertical Gap = 0mm) (All),(InComponentClass(TestPoint'))	0
Height Constraint (Min=0mm) (Max=25.4mm) (Prefered=12.7mm) (All	0
Total	0

Unplated multi-layer pad(s) detected
Pad Free-1(3mm,3mm) on Multi-Layer on Net GNC
Pad Free-1(47mm,3mm) on Multi-Layer on Net GNE
Pad Free-1(47mm,29mm) on Multi-Layer on Net GNC
Pad Free-1(3mm,29mm) on Multi-Layer on Net GNC